ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® International and Pa	IPC. Bannockl	ourn Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration en	on of the sub compasses	ostances w all lower	within the manufactur level materials for w	rer listed i hich the n	tem. Note: nanufacture	if the item is an as or has engineering	sembly with low responsibility.
	21.1 IPC Web Site for Information on IPC-1752 Standard For http://www.ipc.org/IPC-175x Di				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				als and Mfg Information				
upplier Information													
Company name* Comp			ompany unique ID			Unique ID Authority				Response Date*			
nsemi										2025-06-07			
ntact Name Title - Contact			et]	Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Representative			resentative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product I			oduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	n Number	Mfr Item Name			Effective Date	Version	M	anufacturing Site		Weight*	UOM	Unit Type
	2SC3647	2SC3647T-TD-E BIP NPN 2		J 2A 100V		2025-06-07		Cì	CNG		51.58	mg	Each
Ianufacturing Proccess Informa	ation							·					
Terminal Plating / Grid Array M	Iaterial 7	Terminal Base A	Alloy	loy J-STD-020 MSL Rati		Peak Proce	ess Body Temperature Max Tim		Max Time at Peak	ak Temperature Numb		ber of Reflow Cyc	les
contains Bi CU Alloy		CU Alloy		1		260		С	30	secon	ds 3		
omments													
vel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds										
or more information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.67	mg	Supplier	Silicon (Si)	7440-21-3		0.67	mg
Die Attach Solder	0.31	mg	Supplier	Silver (Ag)	7440-22-4		0.0078	mg
			А	Lead (Pb)	7439-92-1	7a	0.2868	mg
			Supplier	Tin (Sn)	7440-31-5		0.0155	mg
Lead Frame	22.4	mg	Supplier	Silver (Ag)	7440-22-4		0.0986	mg
			Supplier	Tin (Sn)	7440-31-5		0.0314	mg
			Supplier	Copper (Cu)	7440-50-8		22.2701	mg
Mold Compound-Black	27.35	mg		Brominated epoxy resin	proprietary data		0.3829	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		1.2308	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2461	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2735	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		20.5125	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		4.6495	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.0547	mg
Plating	0.77	mg	В	Bismuth (Bi)	7440-69-9		0.0046	mg
			Supplier	Tin (Sn)	7440-31-5		0.7654	mg
Wire Bond - Au	0.08	mg	Supplier	Gold (Au)	7440-57-5		0.08	mg